### **Peak EMI Reducing Solution**

#### **Features**

- Generates an EMI optimized clock at the output.
- Input frequency: 25 MHz.
- Frequency outputs:
  - o 60 MHz (unmodulated)
  - o 2 x 48 MHz (unmodulated)
  - o 66.6 MHz (modulated): -1.7% down spread
- Modulation rate: 30 KHz.
- Supply voltage range: 3.3V ± 0.3V.
- Available in 8-pin SOIC Package.
- Commercial and Industrial Temperature range.
- RoHS Compliant

#### **Product Description**

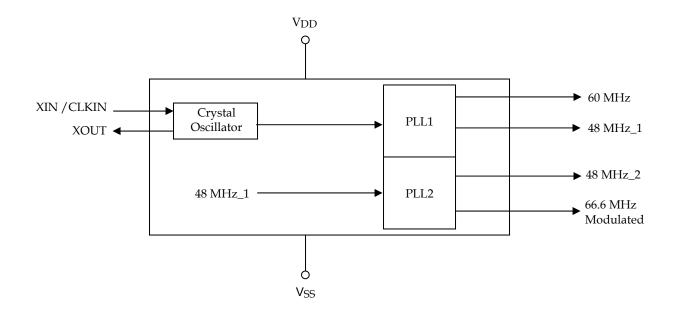
The ASM3P2111B is a versatile spread spectrum frequency modulator that reduces electromagnetic interference (EMI) at the clock source. The ASM3P2111B

allows significant system cost savings by reducing the number of circuit board layers and shielding that are required to pass EMI regulations. The ASM3P2111B modulates the output of PLL in order to spread the bandwidth of a synthesized clock, thereby decreasing the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most clock generators. Lowering EMI by increasing a signal's bandwidth is called spread spectrum clock generation.

#### **Applications**

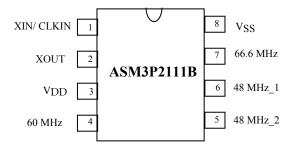
ASM3P2111B is targeted towards EMI management for high speed digital applications such as PC peripheral devices, consumer electronics and embedded controller systems.

#### **Block Diagram**





# **Pin Configuration**



## **Pin Description**

Pin #	Pin Name	Type	Description
1	XIN / CLKIN	I	Connection to crystal
2	XOUT	0	Connection to crystal
3	$V_{DD}$	Р	Power supply for the analog and digital blocks (+3.3V)
4	60 MHz	0	Clock output-1 60 MHz un-modulated
5	48 MHz_2	0	Clock output-2 48 MHz_2 un-modulated
6	48 MHz_1	0	Clock output-3 48 MHz_1 un-modulated
7	66.6 MHz	0	Clock output-4 66.6 MHz modulated
8	V <sub>SS</sub>	Р	Ground to entire chip. Connect to System Ground



# **Absolute Maximum Ratings**

Parameter	Rating	Unit
Voltage on any pin with respect to Ground	-0.5 to +7.0	V
Storage temperature	-65 to +125	°C
Operating temperature	0 to 70	°C
Max. Soldering Temperature (10 sec)	260	°C
Junction Temperature	150	°C
Static Discharge Voltage (As per JEDEC STD 22- A114-B)	2	KV
	Voltage on any pin with respect to Ground  Storage temperature  Operating temperature  Max. Soldering Temperature (10 sec)  Junction Temperature  Static Discharge Voltage	Voltage on any pin with respect to Ground  -0.5 to +7.0  Storage temperature  Operating temperature  0 to 70  Max. Soldering Temperature (10 sec)  Junction Temperature  Static Discharge Voltage

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

### **Operating Conditions**

Parameter	Symbol	Condition / Description	Min	Тур	Max	Unit
Supply Voltage	$V_{DD}$	$3.3V \pm 0.3V$	3	3.3	3.6	V
Crystal Resonator Frequency	F <sub>XIN</sub>		25	-	-	MHz
Output Driver Load Capacitance	CL		-	-	15	pF



rev 0.1

### **DC Electrical Characteristics**

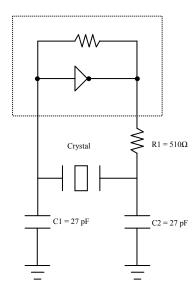
Parameter	Symbol	nbol Conditions / Description		Тур	Max	Unit	
Overall							
Supply Current, Dynamic	I <sub>DD</sub>	V <sub>DD</sub> =3.3V, F <sub>CLK</sub> =25MHz, C <sub>L</sub> =15pF	41	48	62	mA	
Supply Current, Static	I <sub>DDL</sub>	V <sub>DD</sub> = 3.3V, Clock Input = 0	20	25	35	mA	
All input pins							
High-Level Input Voltage	V <sub>IH</sub>	V <sub>DD</sub> =3.3V	2.0	-	V <sub>DD</sub> +0.3	V	
Low-Level Input Voltage	V <sub>IL</sub>	V <sub>DD</sub> =3.3V	V <sub>SS</sub> -0.3	-	0.8	V	
High-Level Input Current	I <sub>IH</sub>		-1	-	1	μΑ	
Low-Level Input Current (pull-up)	I <sub>IL</sub>		-20	-36	-80	μΑ	
High-Level Output Source Current	I <sub>xOH</sub>	$V_{DD}=V (XIN) = 3.3V, V_{O}=0.4V$	-	3	-	mA	
Low-Level Output Sink Current	I <sub>xOL</sub>	V <sub>DD</sub> =3.3V, V (XIN)=V <sub>O</sub> =2.5V	-	3	-	mA	
Clock Outputs							
High-Level Output Source Current	Іон	V <sub>O</sub> =2.5V	-	-20	-	mA	
Low-Level Output Sink Current	I <sub>OL</sub>	V <sub>O</sub> =0.4V	-	23	-	mA	
Output Impedance	Zон	V <sub>O</sub> =0.5V <sub>DD</sub> ; output driving high	-	29	-	Ω	
Catput Impedance	Z <sub>OL</sub>	Vo=0.5V <sub>DD</sub> ; output driving low	-	27	-	<u> </u>	

### **AC Electrical Characteristics**

Parameter	Symbol	Conditions/ Description	Min	Тур	Max	Unit
Rise Time	t <sub>r</sub>	$V_0 = 0.8V \text{ to } 2.0V;$ $C_L = 15pF$	300	800	900	pS
Fall Time	t <sub>f</sub>	$V_{O} = 2.0V \text{ to } 0.8V;$ $C_{L} = 15pF$	360	800	900	pS
Clock Duty Cycle	45	-	55	%		



# **Typical Crystal Oscillator Circuit**



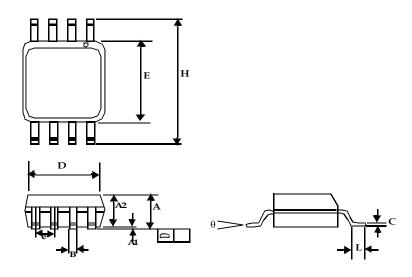
# **Typical Crystal Specifications**

Fundamental AT cut parallel resonant crystal					
Nominal frequency	25 MHz				
Frequency tolerance	± 50 ppm or better at 25°C				
Operating temperature range	-25°C to +85°C				
Storage temperature	-40°C to +85°C				
Load capacitance	18pF				
Shunt capacitance	7pF maximum				
ESR	25 Ω				



# **Package Information**

# 8-Pin SOIC Package



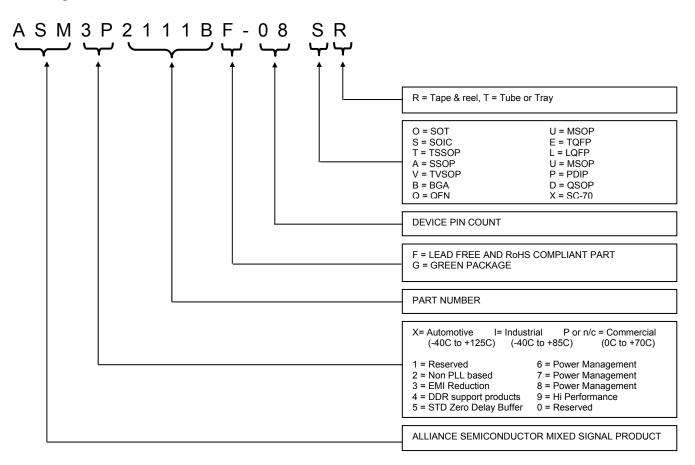
	Dimensions				
Symbol	Inc	hes	Millimeters		
	Min	Max	Min	Max	
A1	0.004	0.010	0.10	0.25	
Α	0.053	0.069	1.35	1.75	
A2	0.049	0.059	1.25	1.50	
В	0.012	0.020	0.31	0.51	
С	0.007	0.010	0.18	0.25	
D	0.193 BSC		4.90 BSC		
Е	0.154 BSC		3.91 BSC		
е	0.050 BSC		1.27 BSC		
Н	0.236 BSC		6.00	BSC	
L	0.016	0.050	0.41	1.27	
θ	0°	8°	0°	8°	



rev 0.1
Ordering Codes

Part number	Marking	Package Configuration	Temperature Range
ASM3P2111BF-08ST	3P2111BF	8-pin SOIC TUBE, Pb Free	Commercial
ASM3P2111BF-08SR	3P2111BF	8-pin SOIC TAPE & REEL, Pb Free	Commercial
ASM3I2111BF-08ST	3I2111BF	8-pin SOIC TUBE, Pb Free	Industrial
ASM3I2111BF-08SR	3I2111BF	8-pin SOIC TAPE & REEL, Pb Free	Industrial
ASM3P2111BG-08ST	3P2111BG	8-pin SOIC TUBE, Green	Commercial
ASM3P2111BG-08SR	3P2111BG	8-pin SOIC TAPE & REEL, Green	Commercial
ASM3I2111BG-08ST	3l2111BG	8-pin SOIC TUBE, Green	Industrial
ASM3I2111BG-08SR	3I2111BG	8-pin SOIC TAPE & REEL, Green	Industrial

### **Ordering Information**



Licensed under US patent #5,488,627, #6,646,463 and #5,631,920.





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Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to Alliance Semiconductor, dated 11-11-2003

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